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Date	2020.01.29

## Soldering Guidance

<b>Product :</b>	<b>SUPERCAPACITOR</b>
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※ The document is the guidance when soldering VINATech's EDLC onto a PCB board.

Head Office : 15 Unam-ro, Deokjin-gu, Jeonju-si, Jeollabuk-do, 561-202, Korea

(837-1 Palbok-Dong 2-ga)

Tel : 82-63-715-3020(Rep.)

Fax : 82-63-715-3021

Sales Office : (AcroTower) B-607, Simindae-ro 230, Dongan-gu, Anyang-si, Gyeonggi-do,

14067, Korea

Tel : 82-31-448-3066(Rep.)

Fax : 82-31-448-3067



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Document number	VNP-MTSG-001
Date of preparation	2020.01.29
Revision number	0
Page	1

## 1. Note

If the soldering temperature is too high or soldering time is too long, the characteristic of the product can be deteriorated or swollen.

If the soldering temperature is high or soldering time is long, sleeve can be cracked, dented, or melted.

The soldering process must be proceeded after connecting the PCB and the product.

Also, when connecting PCB and the product, the product must be covered up the sleeve.

Do not dip the product into melted solder.

During the soldering process, melted lead must be contacted with terminal of the product only.

## 2. Wave soldering

Recommended condition

Solder composition : 99.3Sn-0.7Cu

Solder pot temperature : 250~270°C

Max. Exposure time : 10 sec

Max. preheat temperature (PCB bottom) : 160°C

Max. preheat time (above temperature 100°C) : 60 sec

## 3. Manual soldering

Recommended condition

Temperature of the soldering rod tip : 350°C (Pb solder) and 400°C (Pb-free solder)

Max. soldering duration : 5sec

Do not touch the product with the soldering rod.

## 4. Reflow soldering

Do not use reflow soldering of the product.